

Version With Markings To Show Changes Made

In the claims:

Claims 1 and 2 have been amended as follows:

1. (amended) A method of protecting debris-intolerant micromechanical devices, said method comprising:
 - attaching a device to a package substrate, said device having at least one debris-generating region ~~which source debris over the lifetime of said device~~, and at least one debris-intolerant region; ~~and~~
 - encapsulating at least one of said debris-generating regions with a blocking material, said blocking material avoiding contact with said debris-intolerant region; and
 - attaching a package lid to said package substrate, to enclose said device and said blocking material.
2. (amended) The method of Claim 1, said attaching step further comprising:
 - attaching a device to a substrate, said device having at least one said debris-generating region comprising a sidewall ~~formed where said device was attached to a wafer.~~